

### DESCRIPTION:

TVS diodes can be used in a wide range of applications which like consumer electronic products, automotive industries, munitions, telecommunications, aerospace industries, and intelligent control systems.



SMB

### FEATURES:

- ✧ Glass passivated or planar junction
- ✧ Excellent clamping capability
- ✧ Repetition rate (duty cycle): 0.01%
- ✧ Typical  $I_R$  less than  $1\mu A$  above 10V.
- ✧ Low profile package and low inductance
- ✧ 600W Peak Pulse power capability at  $10 \times 1000\mu s$  waveform.
- ✧ Fast response time: typically less than 1.0ps from 0V to  $V_{BR}$  min.
- ✧ High temperature soldering:  $260^\circ C/10s$  at terminals.
- ✧ Plastic package has Underwriters Laboratory Flammability 94V-0.
- ✧ For surface mounted applications in order to optimize board space

Symbol



Bi-directional

### ABSOLUTE MAXIMUM RATINGS ( $T_A=25^\circ C$ , RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Storage temperature range	$T_{stg}$	-55 to +125	$^\circ C$
Operating junction temperature range	$T_j$	-55 to +125	$^\circ C$
Steady state power dissipation at $T_L=75^\circ C$	$P_{M(AV)}$	5.0	W
Peak pulse power dissipation on 10/1000 $\mu s$ waveform	$P_{PP}$	600	W
Maximum Instantaneous Forward Voltage at 50A for Unidirectional	$V_F$	5.0	V

## ELECTRICAL CHARACTERISTICS (T<sub>A</sub>=25°C)

PART NUMBER	REVERSE STAND-OFF VOLTAGE	BREAKDOWN VOLTAGE VBR(V)MAX.@IT		TEST CURRENT	REVERSE LEAKAGE @VRWM	PEAK PULSE CURRENT	MAXIMUM CLAMPING VOLTAGE @Ipp
		VBR MIN(V)	VBR MAX(V)				
BI-POLAR	VRWM (V)	VBR MIN(V)	VBR MAX(V)	IT (mA)	IR (μA)	Ipp (A)	Vc (v)
6LM33CA	33	36.70	40.60	1	1	26.32	30.1

① Surge waveform: 10/1000μs

V<sub>R</sub>: Stand-off voltage -- Maximum voltage that can be applied

V<sub>BR</sub>: Breakdown voltage

V<sub>C</sub>: Clamping voltage -- Peak voltage measured across the suppressor at a specified I<sub>PP</sub>

I<sub>R</sub>: Reverse leakage current

## RATINGS AND V-I CHARACTERISTICS CURVES (T<sub>A</sub>=25°C, unless otherwise noted)

FIG.1: V- I curve characteristics

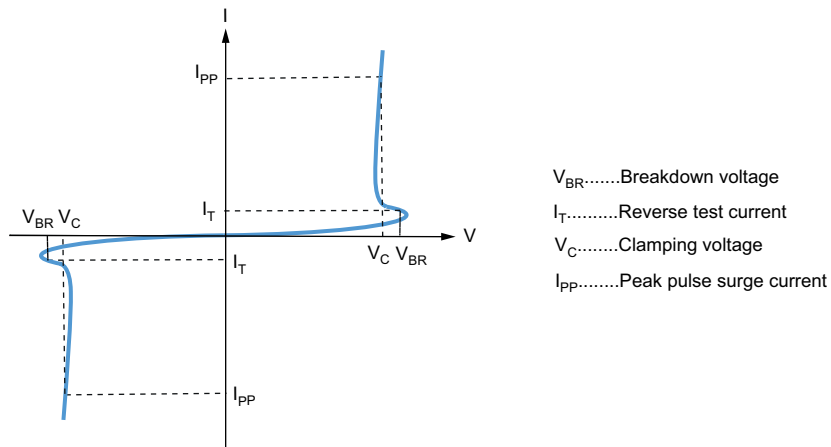


FIG.2: Pulse waveform

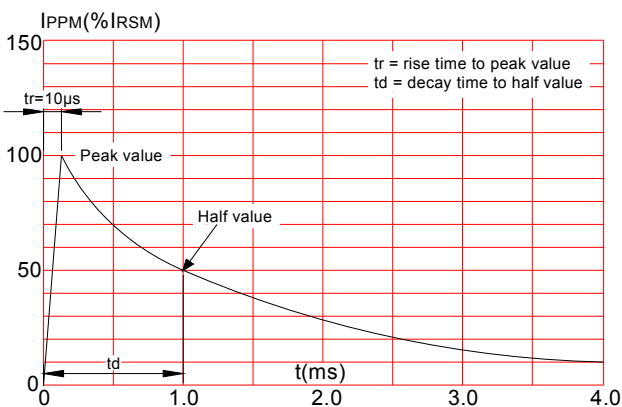
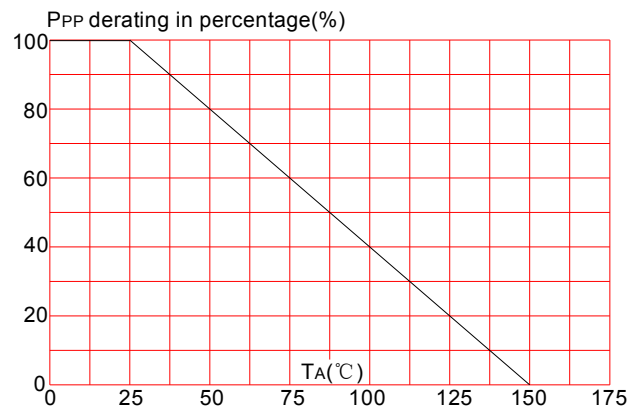
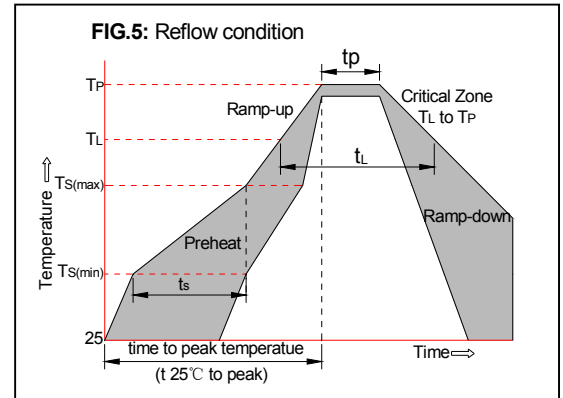


FIG.3: Pulse derating curve

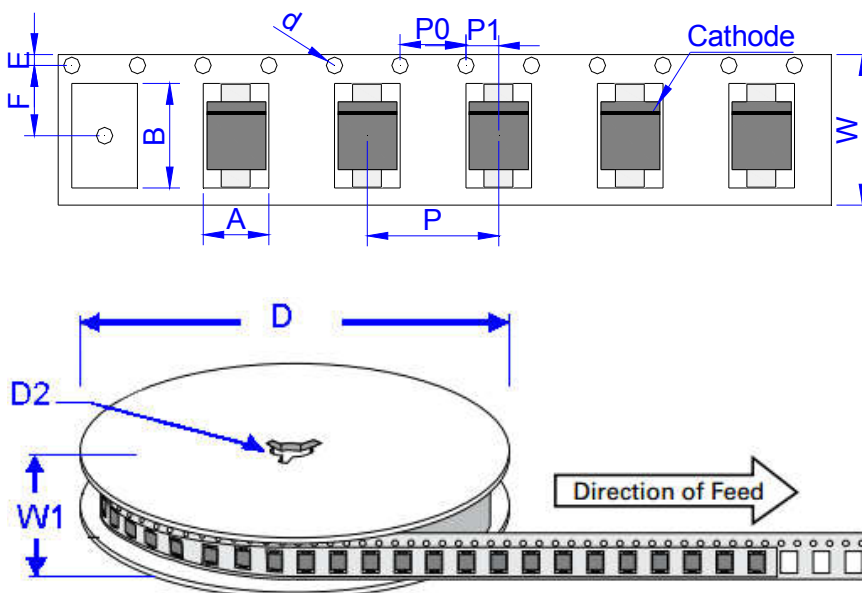


### SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see FIG.5)
Pre Heat	-Temperature Min ( $T_{s(min)}$ )	+150°C
	-Temperature Max( $T_{s(max)}$ )	+200°C
	-Time (Min to Max) ( $t_s$ )	60-180 secs.
Average ramp up rate (Liquid us Temp ( $T_L$ ) to peak)		3°C/sec. Max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature( $T_L$ )(Liquid us)	+217°C
	-Temperature( $t_L$ )	60-150 secs.
Peak Temp ( $T_p$ )		+260(+0/-5)°C
Time within 5°C of actual Peak Temp ( $t_p$ )		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp ( $T_p$ )		8 min. Max
Do not exceed		+260°C

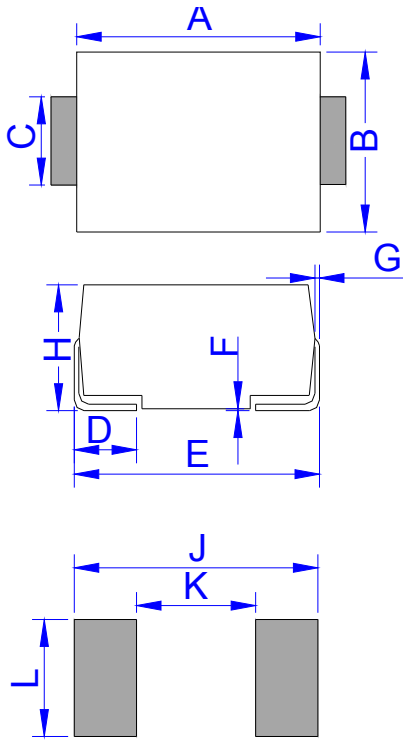


### TAPE AND REEL SPECIFICATION-SMB



Ref.	Dimensions	
	Millimeters	Inches
A	3.76 ± 0.2	0.144 ± 0.012
B	5.69 ± 0.2	0.244 ± 0.012
d	1.5 ± 0.25	0.059 ± 0.004
D	330.0	13.0
D2	13 ± 1	0.512 ± 0.039
E	1.75 ± 0.2	0.059 ± 0.008
F	5.5 ± 0.1	0.222 ± 0.008
P	8.0 ± 0.2	0.315 ± 0.008
P0	4.0 ± 0.2	0.157 ± 0.008
P1	2.0 ± 0.2	0.079 ± 0.008
W	12.0 ± 0.3	0.472 ± 0.008
W1	16.8 ± 2.0	0.661 ± 0.079

PACKAGE MECHANICAL DATA



DO-214AA (SMB)

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.25	4.75	0.167	0.187
B	3.30	3.94	0.130	0.155
C	1.85	2.21	0.073	0.087
D	0.76	1.52	0.030	0.060
E	5.08	5.59	0.200	0.220
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	2.11	2.44	0.083	0.096
J	6.80		0.270	
K		2.60		0.100
L	2.40		0.090	

PART No.	PACKAGE	QUANTITY	TAPE & REEL
6LM33CA	SMB(DO-214AA)	3,000	13 inch

NOTICE

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